	Type	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	5	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3) with troubleshoot$3 and micro-fabrication	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:35	
2	BRS	1296	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 07:54	
3	BRS	440	714/46.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 07:54	
4	BRS	82	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3) with troubleshoot$3 and (micro-fabrication or fabrication) with (semiconductor$1 or wafer$1 or IC$1 or integrated adj circuit$1) or chip$1 or die$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:34	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	8391	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 07:54	
6	BRS	60	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1 and software	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:36	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
7	BRS	5	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1 and software with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:49	
8	BRS	7	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with beam$1 and software with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:16	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
9	BRS	21	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with beam$1 and (program$4 or software$1) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:49	
10	BRS	15	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (program$4 or software$1) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:10	

Type	Hits	Search Text	DBs	Time Stamp	Comments
11 BRS	5	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (program$4 or software$1 or cod$3) with execut$3 and user$1 with interface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:12	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
12	BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (tow or dual) with charg$3 with beam$1 and (program$4 or software$1) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:12	
13	BRS	3	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (tow or dual) with charg$3 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:13	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
14	BRS	0	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with troubleshoot$3 and (micro-fabrication or fabrication) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and high with resolution with image$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:13	
15	BRS	2	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with troubleshoot$3 and (micro-fabrication or fabrication) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and high with resolution with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:13	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
16	BRS	1173	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:17	
17	BRS	184	(troubleshoot$3 or inspect$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:17	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
18	BRS	70	(troubleshoot$3 or inspect$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3 and defect$1 with (file$1 dor database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:17	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
19	BRS	1	(troubleshoot$3 or inspect$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3 and initial$2 with defect$1 with (file$1 dor database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:18	
20	BRS	107	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and chemical$2 with analy$4 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:18	

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	Type	Hits	Search Text	DBs	Time Stamp	Comments
21	BRS	4	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and chemical$2 with analy$4 with exposed with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:20	
22	BRS	11	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and chemical$2 with analy$4 with expos$3 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:20	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
23	BRS	7	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and EDS with tool$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:21	
24	BRS	142	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:25	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
25	BRS	1	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) with EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:25	
26	BRS	3	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) same EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
27	BRS	307	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or IC$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and chemical$2 with analy$4 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:26	
28	BRS	46	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or IC$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) with chemical$2 with analy$4 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:26	

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	Type	Hits	Search Text	DBs	Time Stamp	Comments
29	BRS	4	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) with chemical$2 with analy$4 with expos$3 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:27	
30	BRS	3	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and two with charg$3 with particle$1 with beam$1 and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:27	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
31	BRS	5	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:28	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
32	BRS	2	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) same charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:31	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS	711	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 devices with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:31	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
34	BRS	2	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (dual or two) with charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:28	
35	BRS	2	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (dual or two) with charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:28	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
36	BRS	12	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (dual or two) with charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:29	
37	BRS	0	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and dual with charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
38	BRS	5	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and dual with charg$3 with particle$1 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:32	
39	BRS	6	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and dual same charg$3 with particle$1 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
40	BRS	45	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (two or dual) with charg$3 with particle$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:32	
41	BRS	12	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (two or dual) adj beams and charg$3 with particle$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:33	

Type	Hits	Search Text	DBs	Time Stamp	Comments
42 BRS	5	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:33	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
43	BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:35	

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	Type	Hits	Search Text	DBs	Time Stamp	Comments
44	BRS	5	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$ and (program$4 or software$1 or cod$3) with execut$3 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:36	

11/28/05, EAST Version: 2.0.1.4

	Type	Hits	Search Text	DBs	Time Stamp	Comments
45	BRS	58	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:37	
46	BRS	16	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:37	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
			(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with			
47	BRS	18	(semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) with beam$1 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:37	

11/28/05, EAST Version: 2.0.1.4

Type	Hits	Search Text	DBs	Time Stamp	Comments
48 BRS	16	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) adj beam$1 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:38	

11/28/05, EAST Version: 2.0.1.4

	Type	Hits	Search Text	DBs	Time Stamp	Comments
49	BRS	0	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) adj beam$1 and user$1 with (interface or communicat$3) and computer with job$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:38	
50	BRS	773	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with imag$3 with value$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:38	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
51	BRS	53	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with imag$3 with value$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:39	
52	BRS	1	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with charged with particle with beam with parameter$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:39	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
53	BRS	807	702/183.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/11/28 07:53	
54	BRS	2102	702/117,118,183,185.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/11/28 07:53	
55	BRS	873	702/183.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/11/28 07:53	
56	BRS	2251	702/117,118,183,185.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/11/28 07:54	
57	BRS	1388	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/11/28 07:54	
58	BRS	454	714/46.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/11/28 07:54	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
59	BRS	4041	702/117,118,183,185.ccls. or 700/121.ccls. or 714/46.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 07:54	
60	BRS	340	(702/117,118,183,185.ccls. or 700/121.ccls. or 714/46.ccls.) and (analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1).	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:05	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
61	BRS	2	(702/117,118,183,185.ccls. or 700/121.ccls. or 714/46.ccls.) and (analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1 and software	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:19	
62	BRS	4	(702/117,118,183,185.ccls. or 700/121.ccls. or 714/46.ccls.) and (analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:20	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
63	BRS	1	(702/117,118,183,185.ccls. or 700/121.ccls. or 714/46.ccls.) and (analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with beam$1 and software with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:17	
64	BRS	8867	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:19	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
65	BRS	74	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1 and software	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:19	
66	BRS	275	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:20	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
67	BRS	84	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3) with troubleshoot$3 and (micro-fabrication or fabrication) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:34	
68	BRS	5	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3) with troubleshoot$3 and micro-fabrication	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:35	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
69	BRS	74	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1 and software	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:44	
70	BRS	10	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charged with beam$1 and software with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:49	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
71	BRS	27	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with beam$1 and (program$4 or software$1) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 08:49	
72	BRS	89	(702/117,118,183,185.ccls. or 700/121.ccls. or 714/46.ccls.) and (analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1)	US-PGPUB	2005/11/28 09:06	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS 73	18	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (program$4 or software$1) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:10	

11/28/05, EAST Version: 2.0.1.4

Type	Hits	Search Text	DBs	Time Stamp	Comments
74 BRS	6	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (program$4 or software$1 or cod$3) with execut$3 and user$1 with interface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:12	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
75	BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (tow or dual) with charg$3 with beam$1 and (program$4 or software$1) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:12	
76	BRS	3	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (tow or dual) with charg$3 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:13	

Type	Hits	Search Text	DBs	Time Stamp	Comments
77 BRS	0	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with troubleshoot$3 and (micro-fabrication or fabrication) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and high with resolution with image$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:13	
78 BRS	1324	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:17	

Type	Hits	Search Text	DBs	Time Stamp	Comments
		(troubleshoot$3 or inspect$3) with . (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3			
79	BRS 208		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:17	

Type	Hits	Search Text	DBs	Time Stamp	Comments
BRS	80	(troubleshoot$3 or inspect$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3 and defect$1 with (file$1 dor database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:17	

80

	Type	Hits	Search Text	DBs	Time Stamp	Comments
81	BRS	1	(troubleshoot$3 or inspect$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (micro-fabrication or fabrication) and high with resolution with imag$3 and initial$2 with defect$1 with (file$1 dor database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:18	
82	BRS	110	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and chemical$2 with analy$4 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:18	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
83	BRS	11	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and chemical$2 with analy$4 with expos$3 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:20	
84	BRS	7	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and EDS with tool$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:21	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
85	BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and cross with section$2 with three with dimension and EDS with tool$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:21	
86	BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and cross with section$2 with three with dimension and EDS with tool$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:21	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
87	BRS	159	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:22	
88	BRS	159	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:25	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
89	BRS	1	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or integrated adj circuit$1) (or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) with EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:25	
90	BRS	3	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or integrated adj circuit$1) (or chip$1 or die$1) and (cross-section$2 or (cross with section$2)) with (3-d mor dimension$1) same EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
91	BRS	324	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and chemical$2 with analy$4 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:26	
92	BRS	49	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) with chemical$2 with analy$4 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
93	BRS	4	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) with chemical$2 with analy$4 with expos$3 with surface$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:27	
94	BRS	3	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and two with charg$3 with particle$1 with beam$1 and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:27	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
95	BRS	6	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:28	
96	BRS	2	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (dual or two) with charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:28	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
97	BRS	12	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (dual or two) with charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:29	
98	BRS	3	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) same charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:31	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
99	BRS	790	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 devices with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:31	
100	BRS	0	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and dual with charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
101	BRS	5	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or integrated adj circuit$1) or chip$1 or die$1) and dual with charg$3 with particle$1 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:32	
102	BRS	6	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or integrated adj circuit$1) or chip$1 or die$1) and dual same charg$3 with particle$1 with beam$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
103	BRS	45	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (two or dual) with charg$3 with particle$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:32	
104	BRS	12	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) same (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (two or dual) adj beams and charg$3 with particle$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:33	

Type	Hits	Search Text	DBs	Time Stamp	Comments
105 BRS	6	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and (program$4 or software$1 or cod$3) with execut$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:33	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
106	BRS	1	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particles$1 with beams and (program$4 or software$1 or cod$3) with execut$3 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:35	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
107	BRS	6	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$ and (program$4 or software$1 or cod$3) with execut$3 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:36	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
108	BRS	66	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:37	
109	BRS	18	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beams and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:37	

Type	Hits	Search Text	DBs	Time Stamp	Comments
110 BRS	20	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) with beam$1 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:37	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
111	BRS	17	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) adj beam$1 and user$1 with (interface or communicat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:38	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
112	BRS	0	(analy$4 or diagnos$3) with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and charg$3 with particle$1 with beam$1 and (two or dual) adj beam$1 and user$1 with (interface or communicat$3) and computer with job$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:38	
113	BRS	838	(defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with imag$3 with value$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:38	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
114	BRS	56	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with imag$3 with value$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:39	
115	BRS	1	analy$4 with (defect$1 or error$1 or malfunction$2 or problem$1 or fault$1 or fail$3 or anomal$3 or trouble$1) with (semiconductor$1 or wafer$1 or IC$1 or (integrated adj circuit$1) or chip$1 or die$1) and (calibrat$3 or compensat$3 or adjust$3) with charged with particle with beam with parameter$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/28 09:39	

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
1			US 20050251365 A1	20051110	25	System and method for identifying a manufacturing tool causing a fault	702/185		702/185
2	X		US 20050251277 A1	20051110	16	Method and system for problem case packaging	700/110	702/185	702/185
3	X		US 20050251276 A1	20051110		SYSTEM AND METHOD FOR REAL-TIME FAULT DETECTION, CLASSIFICATION, AND CORRECTION IN A SEMICONDUCTOR MANUFACTURING ENVIRONMENT	700/108	700/121; 700/223	700/121
4	X		US 20050240376 A1	20051027	40	Failure diagnosis method, failure diagnosis apparatus, image forming apparatus, program, and storage medium	702/183		702/183
5	X		US 20050234575 A1	20051020		Job flow Petri Net and controlling mechanism for parallel processing	700/97	700/121; 700/95	700/121

U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
6	X	US 20050222281 6 A1	20051006	34	Compactor independent fault diagnosis	702/185		702/185
7	X	US 20050020371 6 A1	20050915		Method and system for delay defect location when testing digital semiconductor devices	702/185		702/185
8	X	US 20050019772 8 A1	20050908		FEATURE TARGETED INSPECTION	700/110	700/121	700/121
9	X	US 20050018764 9 A1	20050825		Method and apparatus for the monitoring and control of a semiconductor manufacturing process	700/121		700/121
10	X	US 20050018764 8 A1	20050825		SEMICONDUCTOR PROCESS AND YIELD ANALYSIS INTEGRATED REAL-TIME MANAGEMENT METHOD	700/110	700/109; 700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
11	X		US 20050182587 A1	20050818		Circuit quality evaluation method and apparatus, circuit quality evaluation program, and medium having the program recorded thereon	702/117		702/117
12	X		US 20050177269 A1	20050811		Method for dynamic sensor configuration and runtime execution	700/121		700/121
13	X		US 20050171627 A1	20050804		Method and apparatus for monitoring tool performance	700/121		700/121
14	X		US 20050159911 A1	20050721		Method and apparatus for automatic sensor installation	702/104	700/121	700/121
15	X		US 20050143853 A1	20050630		Mass-production transfer support system and semiconductor manufacturing system	700/121	700/109	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
16	X		US 20050137736 A1	20050623		Fuzzy reasoning model for semiconductor process fault detection using wafer acceptance test data	700/110	702/185	702/185
17	X		US 20050122510 A1	20050609		System and method for process variation monitor	356/237.2	382/145; 700/121	700/121
18	X		US 20050119852 A1	20050602		Semiconductor test data analysis system	702/118		702/118
19	X		US 20050114064 A1	20050526		Circuit for a parallel bit test of a semiconductor memory device and method thereof	702/117		702/117
20	X		US 20050107984 A1	20050519		Manufacturing apparatus and method for predicting life of rotary machine used in the same	702/183		702/183
21	X		US 20050090923 A1	20050428		Method for monitoring a batch system	700/109	257/E21.525; 700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
22	X		US 20050065630 A1	20050324		Method and apparatus for simplified system configuration	700/121	700/103; 700/108	700/121
23	X		US 20050060681 A1	20050317		USING A PARTIAL METAL LEVEL MASK FOR EARLY TEST RESULTS	716/21	700/121; 716/4	700/121
24	X		US 20050058335 A1	20050317	6	Defect management method	382/141	700/110; 700/121	700/121
25	X		US 20050055121 A1	20050310		System and method for effective field loss analysis for semiconductor wafers	700/110	700/121	700/121
26	X		US 20050049836 A1	20050303		METHOD OF DEFECT ROOT CAUSE ANALYSIS	702/185		702/185
27	X		US 20050049834 A1	20050303		Non-invasive system and method for diagnosing potential malfunctions of semiconductor equipment components	702/183		702/183
28	X		US 20050049811 A1	20050303		System and method for indication of fuse defects based upon analysis of fuse test data	702/117		702/117

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
29	X		US 20050049810 A1	20050303		METHOD AND SYSTEM FOR DETERMINING MINIMUM POST PRODUCTION TEST TIME REQUIRED ON AN INTEGRATED CIRCUIT DEVICE TO ACHIEVE OPTIMUM RELIABILITY	702/117		702/117
30	X		US 20050049737 A1	20050303		Defect analysis sampling control	700/110	700/121; 702/83	700/121
31	X		US 20050027481 A1	20050203		System for making semiconductor devices and processing control thereof	702/183		702/183
32	X		US 20050021303 A1	20050127		Method for analyzing fail bit maps of wafers	702/185		702/185
33	X		US 20040267399 A1	20041230		Feedforward, feedback wafer to wafer control method for an etch process	700/121		700/121
34	X		US 20040262290 A1	20041230		Method and system to process semiconductor wafers	219/490	700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
35	X		US 20040260420 A1	20041223		Processing method and processing system	700/121		700/121
36	X		US 20040220688 A1	20041104		Advanced process control method and advanced process control system for acquiring production data in a chip production installation	700/96	700/121; 700/95	700/121
37	X		US 20040199361 A1	20041007		Method and apparatus for equipment diagnostics and recovery with self-learning	702/183		702/183
38	X		US 20040193381 A1	20040930		METHOD FOR ANALYZING WAFER TEST PARAMETERS	702/118		702/118
39	X		US 20040185583 A1	20040923		Method of operating a system for chemical oxide removal	438/8	700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
40	X		US 2004017346 4 A1	20040909		Method and apparatus for providing intra-tool monitoring and control	205/157	257/E21.5 25; 700/121	700/121
41	X		US 2004015327 4 A1	20040805		Fail analysis device	702/117		702/117
42	X		US 2004014811 9 A1	20040729		Semiconductor test apparatus	702/117		702/117
43	X		US 2004013885 6 A1	20040715		METHOD FOR ANALYZING FINAL TEST PARAMETERS	702/185		702/185
44	X		US 2004013329 4 A1	20040708		Defect alarm system and method	700/110	700/121	700/121
45	X		US 2004011117 6 A1	20040610		In-situ randomization and recording of wafer processing order at process tools	700/121		700/121
46	X		US 2004010918 7 A1	20040610		Image processing apparatus, image processing method and program	358/1.13	358/1.15; 358/1.16; 702/183; 717/174	702/183

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
47	X		US 20040093185 A1	20040513		Using clock gating or signal gating to partition a device for fault isolation and diagnostic data collection	702/185		702/185
48	X		US 20040064212 A1	20040401		Manufacturing apparatus and method for predicting life of rotary machine used in the same	700/108	702/183	702/183
49	X		US 20040059456 A1	20040325		Correlating an inline parameter to a device operation parameter	700/121	257/E21.525	700/121
50	X		US 20040044431 A1	20040304		Methods and systems for controlling reticle-induced errors	700/121		700/121
51	X		US 20040029299 A1	20040212		Dynamic targeting for a process control system	438/5	257/E21.525; 700/121	700/121
52	X		US 20040006404 A1	20040108		Permanent chip ID using FeRAM	700/115	700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
53	X		US 2004000282 9 A1	20040101		Semiconductor test data analysis system	702/118		702/118
54	X		US 2003023664 8 A1	20031225		Memory defect redress analysis treating method, and memory testing apparatus performing the method	702/185		702/185
55	X		US 2003023658 6 A1	20031225		Method for failure analysis and system for failure analysis	700/110	700/121	700/121
56	X		US 2003021246 9 A1	20031113		METHOD FOR AUTOMATICALLY CONTROLLING DEFECT SPECIFICATION IN A SEMICONDUCTOR MANUFACTURING PROCESS	700/121	438/14; 700/110	700/121
57	X		US 2003020833 7 A1	20031106		Apparatus for analyzing a failure of a semiconductor device and method therefor	702/185	257/E21.5 25	702/185

	U	1	Document ID	Issue Date	Page s	Title	Current OR	Current XRef	Retrieval Classif
58	X		US 2003020435 0 A1	20031030		Method and apparatus for measuring the quality of delay test patterns	702/117		702/117
59	X		US 2003020005 6 A1	20031023		Semiconductor device analysis system	702/183		702/183
60	X		US 2003018207 3 A1	20030925		Method of detecting an integrated circuit in failure among integrated circuits, apparatus of doing the same, and recording medium storing program for doing the same	702/118		702/118
61	X		US 2003016321 7 A1	20030828		Semiconductor manufacturing apparatus and its diagnosis apparatus and operating system	700/108	700/121	700/121
62	X		US 2003015870 5 A1	20030821		Method for avoiding irregular shutoff of production equipment and system for avoiding irregular shutoff	702/183	.	702/183

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
63	X		US 2003014954 7 A1	20030807		Method for diagnosing failure of a manufacturing apparatus and a failure diagnosis system	702/183		702/183
64	X		US 2003014950 6 A1	20030807		Method and system to process semiconductor wafers	700/121		700/121
65	X		US 2003013529 5 A1	20030717		Defect source identifier with static manufacturing execution system	700/108	700/109; 700/110; 700/117; 700/121	700/121
66	X		US 2003012589 7 A1	20030703		Semiconductor device testing apparatus having timing calibration function	702/118		702/118
67	X		US 2003010994 5 A1	20030612		Apparatus and method for automatically controlling semiconductor manufacturing process in semiconductor factory automation system	700/95	700/109; 700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
68	X		US 2003010097 0 A1	20030529		Method and system of monitoring apparatuses of manufacturing IC	700/108	700/109; 700/121	700/121
69	X		US 2003009323 7 A1	20030515		Method of detecting an integrated circuit in failure among integrated circuits, apparatus of doing the same, and recording medium storing program for doing the same	702/118		702/118
70	X		US 2003009317 4 A1	20030515		Fabrication process control system emulator	700/121		700/121
71	X		US 2003008838 0 A1	20030508		Method of detecting an integrated circuit in failure among integrated circuits, apparatus of doing the same, and recording medium storing program for doing the same	702/118		702/118

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
72	X		US 20030088379 A1	20030508		Electron beam test system and electron beam test method	702/117		702/117
73	X		US 20030069660 A1	20030410		Process error prevention method in semiconductor fabricating equipment	700/110	700/108; 700/121	700/121
74	X		US 20030060916 A1	20030327		Automatic production quality control method and system	700/121	700/109	700/121
75	X		US 20030040830 A1	20030227		Method and apparatus for providing intra-tool monitoring and control	700/121	257/E21.525; 700/108	700/121
76	X		US 20030036869 A1	20030220		Using clock gating or signal gating to partition a device for fault isolation and diagnostic data collection	702/117		702/117
77	X		US 20020183884 A1	20021205		Method for continuous, non lot-based integrated circuit manufacturing	700/115	700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
78	X		US 20020165636 A1	20021107		Systems and methods for metrology recipe and model generation	700/121		700/121
79	X		US 20020107604 A1	20020808		Run-to-run control method for proportional-integral-derivative (PID) controller tuning for rapid thermal processing (RTP)	700/121	438/14; 700/31; 700/42; 702/40	700/121
80	X		US 20020072878 A1	20020613		Deterioration diagnostic method and equipment thereof	702/183		702/183
81	X		US 20020072872 A1	20020613		Method for diagnosing process parameter variations from measurements in analog circuits	702/117	257/E21.525	702/117
82	X		US 20020069349 A1	20020606		Method and apparatus for control of semiconductor processing for reducing effects of environmental effects	712/224	700/121	700/121

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
83	X		US 20020059012 A1	20020516		Method of manufacturing semiconductor devices	700/121	257/E21.525	700/121
84	X		US 20020059010 A1	20020516		Failure analyzing device for semiconductors	700/110	257/E21.525; 700/109; 700/117; 700/121	700/121
85	X		US 20020035447 A1	20020321		Remote diagnosing system for semiconductor manufacturing equipment and a remote diagnosing method	702/188	257/E21.525; 438/14; 700/108; 700/121; 700/2; 702/183	700/121; 702/183
86	X		US 20020010560 A1	20020124		System for mapping logical functional test data of logical integrated circuits to physical representation using pruned diagnostic list	702/118	702/117	702/117; 702/118

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
87	X		US 20010044669 A1	20011122		System and method to reduce bond program errors of integrated circuit bonders	700/121	700/117	700/121
88	X		US 20010041967 A1	20011115		Semiconductor device testing apparatus and method for testing semiconductor device	702/117		702/117
89	X		US 20010007085 A1	20010705		Method and system for supervising reference wafers on semiconductor device production line and recording medium	700/121	700/115; 700/213; 700/214; 700/219; 700/225	700/121